

Amendments to the Specification:

Please replace the paragraph entitled "Related Applications" located on page 1 of the Specification with the following paragraph:

RELATED APPLICATIONS

This application is a continuation-in-part of U.S. Patent Application No.

[10/645,665 (Attorney Docket No. 2328-026) entitled "Multiple Frequency Plasma Etch Reactor" by Raj Dhindsa, et al. Erie Lenz, Mukund Srinivasan, Aaron Eppler, Felix Kezakevish, Camelia Rusu, Lumin Li, Reza Sadjadi, Jim Tietz, and Jeff Marks filed August 22, 2003, which is incorporated by reference in its entirety.